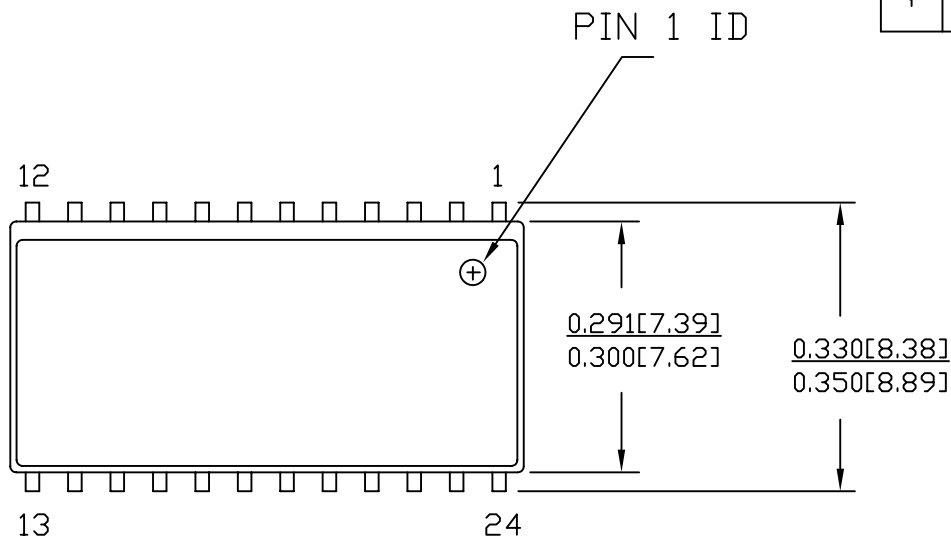


# 24 Lead (300 Mil) Molded SOJ V13

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	N/A	N/A	N/A	N/A
1	-	*A	49387	CHG. DIM. AT *. ADD LEAD COPLANARITY	05/29/97	N/A
1	-	*B	129444	ADD MM DIM./ ADD JEDEC #/ ADD PKG. WEIGHT/ ADD VZ PART #	11/06/03	N/A
1	-	*C	2871406	Changed template, & title from 24LD (300 MIL) SOJ PKG OUTLINE to PACKAGE OUTLINE, 24L SOJ 300 MILS V24.3/VZ24.3 (MOLDED SOJ V13)	02/02/10	QAD
1	-	*D	3388480	Sunset review, no change	09/30/11	QAD
1	-	*E	3769295	Changed package weight from "0.75gms" to "See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress web."	10/08/12	QAD

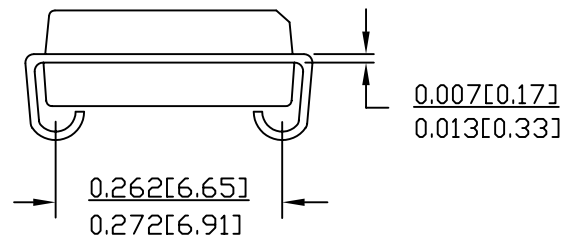
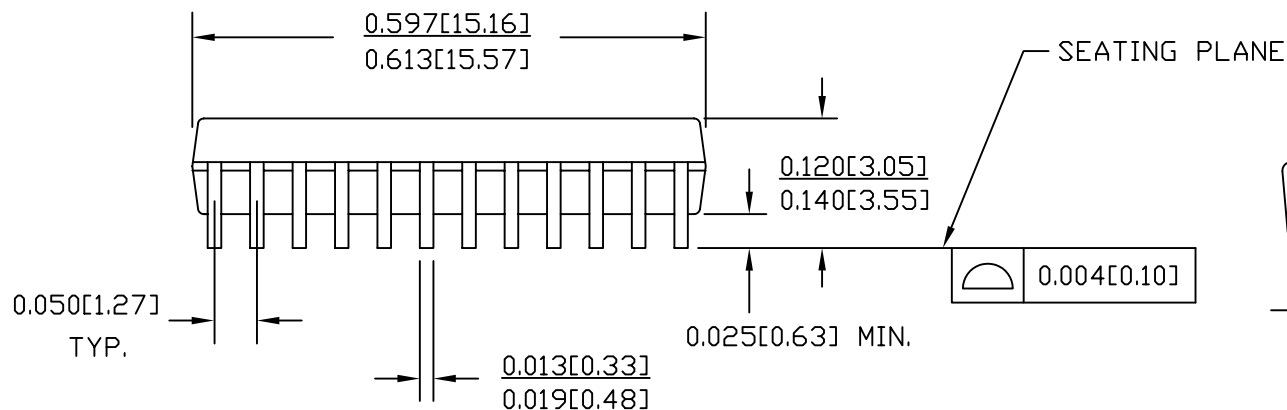


DIMENSIONS IN INCHES[MM] MIN. MAX.


REFERENCE JEDEC MO-088

PACKAGE WEIGHT: SEE CYPRESS PACKAGE MATERIAL DECLARATION DATASHEET (PMDD) POSTED ON CYPRESS WEB.

PART #	
V24.3	STANDARD PKG.
VZ24.3	LEAD FREE PKG.



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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE:  DECIMALS .XX ± 0.05 .XXX ± .XXXX +  ANGLES ± 1°		DESIGNED BY HTN	DATE 11/06/03	 <b>CYPRESS</b> Company Confidential	
		DRAWN BY HTN	DATE 11/06/03		
		CHECKED BY EDCA	DATE 10/08/12		
		APPROVED BY QAD	DATE 10/08/12		
MATERIAL N/A		APPROVED BY CMG	DATE 10/08/12	TITLE PACKAGE OUTLINE, 24L SOJ 300 MILS V24.3/VZ24.3 (MOLDED SOJ V13)	
FINISH N/A		APPROVED BY N/A	DATE N/A	SIZE A	PART NO. V24.3/VZ24.3
				DWG NO 51-85030	REV *E
				SCALED TO FIT N/A	SHEET 1 OF 1